



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|-----------------|
| Case Code | 2D |
| L | 8mm +/-0.38mm |
| W | 4.4mm +/-0.2mm |
| H | 6.2mm +/-0.38mm |
| S | 1.9mm +/-0.38mm |
| F | 3mm +/-0.2mm |
| K | 4.8mm +/-0.38mm |

Packaging Specifications

| | |
|--------------------|------|
| Packaging | Tray |
| Packaging Quantity | 50 |

General Information

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|---------------------|--|
| Series | TSP |
| Dielectric | Polymer Tantalum |
| Style | Stacked Chip |
| Description | SMD, Polymer, KO, Stacks, High Reliability |
| Features | High Reliability |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov |
| SCIP Number | 30e82d35-b509-48ec-8c77-2d5ec01b3abc |
| Termination | Solder Coated |
| Termination (Stack) | Silver Plated |
| AEC-Q200 | No |
| MSL | 3 |

Specifications

| | |
|-------------------------|-------------------------------|
| Capacitance | 440 uF |
| Capacitance Tolerance | 20% |
| Voltage DC | 10 VDC (105C), 6.7 VDC (125C) |
| Temperature Range | -55/+125°C |
| Rated Temperature | 105°C |
| Dissipation Factor | 10% 120Hz 25C |
| Failure Rate | N/A |
| Resistance | 13 mOhms (100kHz 25C) |
| Leakage Current | 440 uA (5min 25°C) |
| Testing and Reliability | 4 Cycles At +25C +/-5C |